

**1 Mbps, OPEN COLLECTOR OUTPUT, FOR GATE DRIVE INTERFACE  
HIGH CMR, INTELLIGENT POWER MODULE  
5-PIN SOP PHOTOCOUPLER**

–NEPOC Series–

**DESCRIPTION**

The PS9713 is an optically coupled isolator containing a GaAlAs LED on the input side and a photo diode and a signal processing circuit on the output side on one chip.

**FEATURES**

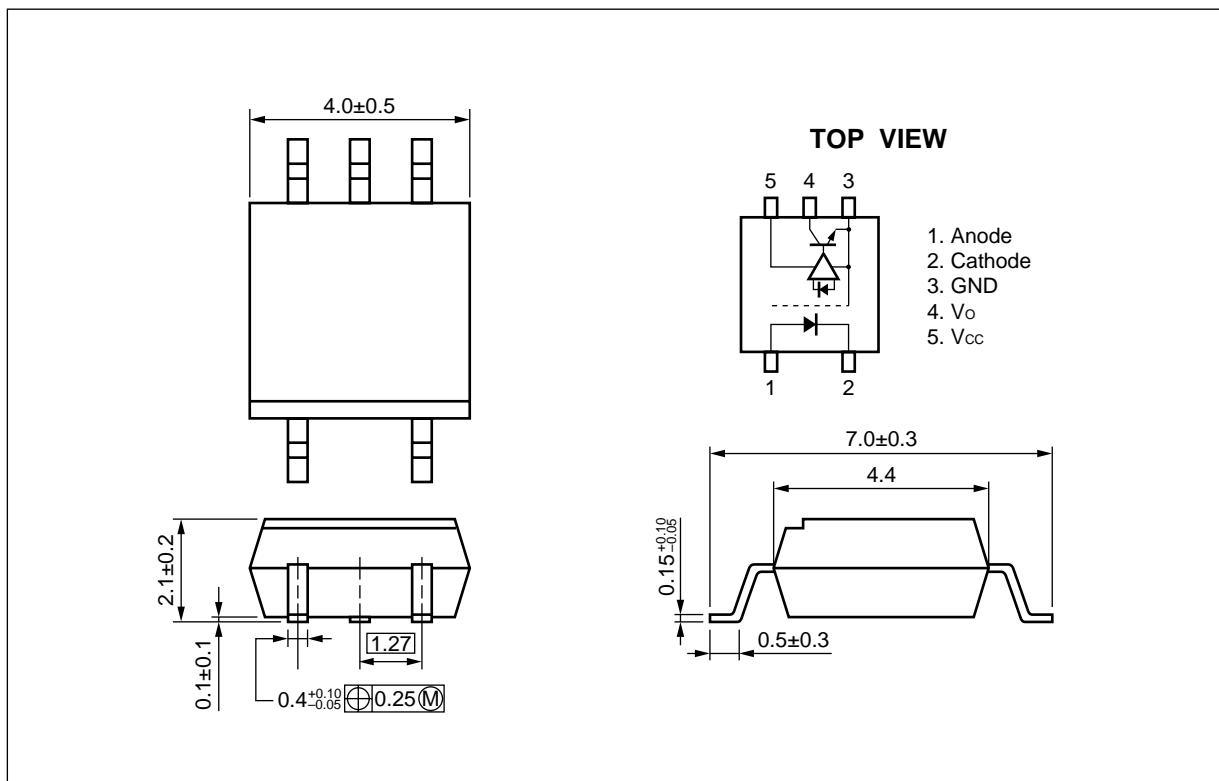
- High instantaneous common mode rejection voltage ( $CM_H$ ,  $CM_L = \pm 15 \text{ kV}/\mu\text{s}$  MIN.)
- Small and thin package (5-pin SOP)
- High-speed response ( $t_{PHL} = 500 \text{ ns}$  MAX.,  $t_{PLH} = 750 \text{ ns}$  MAX.)
- Maximum propagation delays ( $t_{PLH} - t_{PHL} = 270 \text{ ns}$  TYP.)
- Pulse width distortion ( $|t_{PHL} - t_{PLH}| = 270 \text{ ns}$  TYP.)
- Ordering number of taping product: PS9713-F3, F4: 3 500 pcs/reel
- Safety standards
  - UL approved: File No. E72422 (S)
  - VDE0884 approved (Option)

**APPLICATIONS**

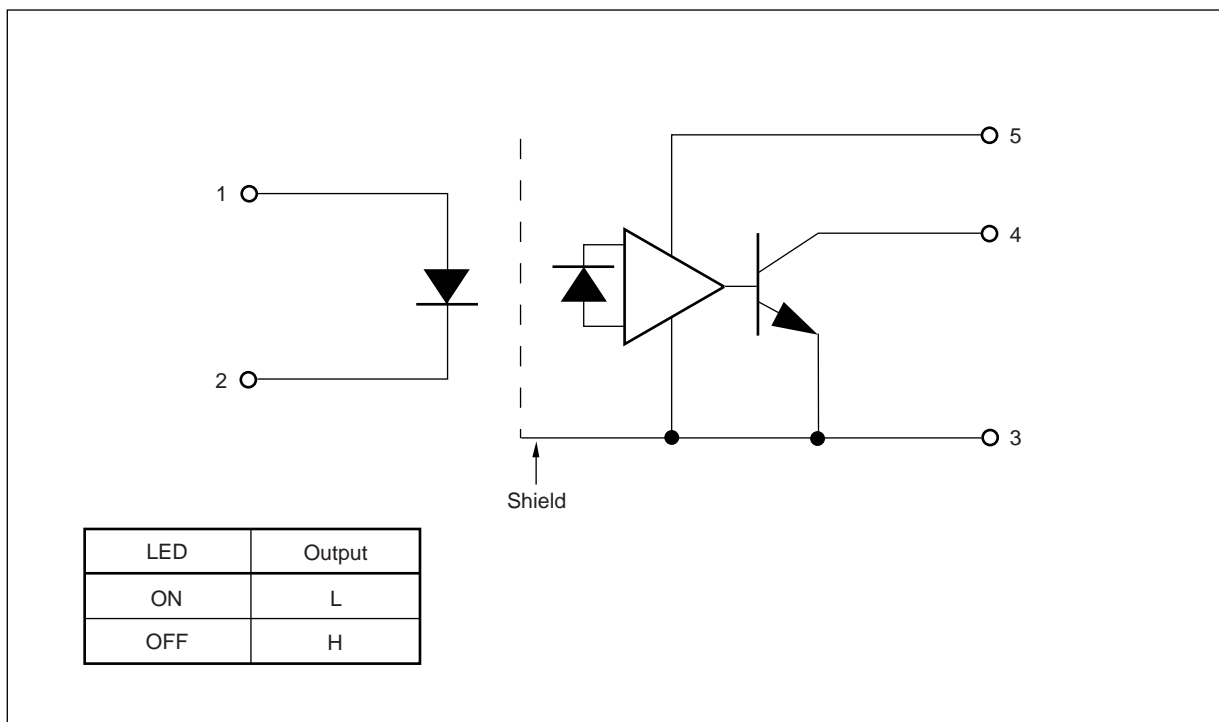
- IPM Driver
- General purpose inverter

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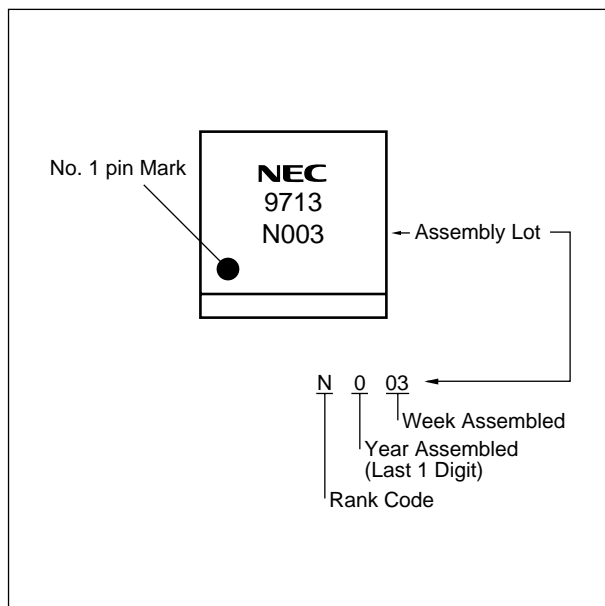
★ PACKAGE DIMENSIONS (UNIT: mm)



★ FUNCTIONAL DIAGRAM



★ MARKING EXAMPLE



★ ORDERING INFORMATION

Part Number		Package	Packing Style	Application Part Number <sup>*1</sup>
Standard Products	VDE0884 Approved Products (Option)			
PS9713	PS9713-V	5-pin SOP	Magazine case 100 pcs	PS9713
PS9713-F3	PS9713-V-F3		Embossed tape 3 500 pcs/reel	
PS9713-F4	PS9713-V-F4			

\*1 For the application of the Safety Standard, following part number should be used.

**ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C, unless otherwise specified)**

★

Parameter		Symbol	Ratings	Unit
Diode	Forward Current	I <sub>F</sub>	25	mA
	Reverse Voltage	V <sub>R</sub>	5	V
Detector	Supply Voltage	V <sub>CC</sub>	−0.5 to +35	V
	Output Voltage	V <sub>O</sub>	−0.5 to +35	V
	Output Current	I <sub>O</sub>	15	mA
	Power Dissipation	P <sub>C</sub>	100	mW
Isolation Voltage <sup>*1</sup>		BV	2 500	Vr.m.s.
Operating Ambient Temperature		T <sub>A</sub>	−40 to +100	°C
Storage Temperature		T <sub>stg</sub>	−55 to +125	°C

\*1 AC voltage for 1 minute at T<sub>A</sub> = 25°C, RH = 60% between input and output.

**RECOMMENDED OPERATING CONDITIONS**

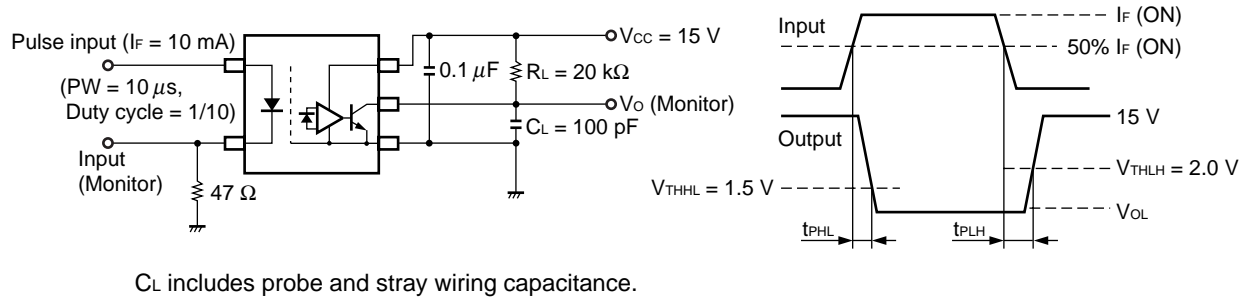
Parameter	Symbol	MIN.	TYP.	MAX.	Unit
High Level Input Current	I <sub>FH</sub>	10		20	mA
Output Voltage	V <sub>O</sub>	0		30	V
Supply Voltage	V <sub>CC</sub>	4.5		30	V
LED Off Voltage	V <sub>F</sub>	0		0.8	V

**ELECTRICAL CHARACTERISTICS ( $T_A = -40$  to  $+100^\circ\text{C}$ ,  $V_{CC} = 15\text{ V}$ , unless otherwise specified)**

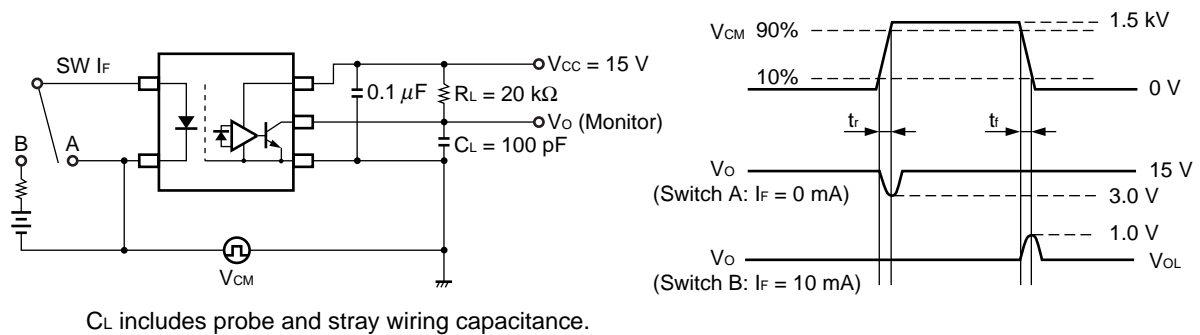
Parameter		Symbol	Conditions	MIN.	TYP. <sup>1)</sup>	MAX.	Unit
Diode	Forward Voltage	$V_F$	$I_F = 10\text{ mA}$	1.3	1.65	2.1	V
	Reverse Current	$I_R$	$V_R = 3\text{ V}$			200	$\mu\text{A}$
	Terminal Capacitance	$C_t$	$V = 0\text{ V}$ , $f = 1\text{ MHz}$ , $T_A = 25^\circ\text{C}$		30		pF
Detector	Low Level Output Voltage	$V_{OL}$	$I_F = 10\text{ mA}$ , $V_{CC} = 5\text{ V}$ , $I_{OL} = 2.4\text{ mA}$		0.13	0.6	V
	High Level Output Current	$I_{OH}$	$V_{CC} = 30\text{ V}$ , $V_F = 0.8\text{ V}$		0.01	50	$\mu\text{A}$
	High Level Supply Current	$I_{CCH}$	$V_{CC} = 30\text{ V}$ , $V_F = 0.8\text{ V}$ , $V_O = \text{open}$		0.6	1.3	mA
	Low Level Supply Current	$I_{CCL}$	$V_{CC} = 30\text{ V}$ , $I_F = 10\text{ mA}$ , $V_O = \text{open}$		0.6	1.3	mA
Coupled	Threshold Input Current ( $H \rightarrow L$ )	$I_{FHL}$	$V_O = 0.8\text{ V}$ , $I_O = 0.75\text{ mA}$		1.5	5.0	mA
	Current Transfer Ratio ( $I_C/I_F$ )	CTR	$I_F = 10\text{ mA}$ , $V_O = 0.6\text{ V}$	44	110		%
	Isolation Resistance	$R_{I-O}$	$V_{I-O} = 1\text{ kV}_{DC}$ , $R_H = 40$ to $60\%$ , $T_A = 25^\circ\text{C}$	$10^{11}$			$\Omega$
	Isolation Capacitance	$C_{I-O}$	$V = 0\text{ V}$ , $f = 1\text{ MHz}$ , $T_A = 25^\circ\text{C}$		0.6		pF
	Propagation Delay Time ( $H \rightarrow L$ ) <sup>2)</sup>	$t_{PHL}$	$I_F = 10\text{ mA}$ , $R_L = 20\text{ k}\Omega$ , $C_L = 100\text{ pF}$ , $V_{THHL} = 1.5\text{ V}$ , $V_{THLH} = 2.0\text{ V}$		250	500	ns
	Propagation Delay Time ( $L \rightarrow H$ ) <sup>2)</sup>	$t_{PLH}$			520	750	
	Maximum Propagation Delays	$t_{PLH}-t_{PHL}$		-200	270	650	
	Pulse Width Distortion (PWD) <sup>2)</sup>	$ t_{PHL}-t_{PLH} $			270	650	
	Common Mode Transient Immunity at High Level Output <sup>3)</sup>	$CM_H$	$T_A = 25^\circ\text{C}$ , $I_F = 0\text{ mA}$ , $V_O > 3.0\text{ V}$ , $V_{CM} = 1.5\text{ kV}$ , $R_L = 20\text{ k}\Omega$ , $C_L = 100\text{ pF}$	15			kV/ $\mu\text{s}$
	Common Mode Transient Immunity at Low Level Output <sup>3)</sup>	$CM_L$	$T_A = 25^\circ\text{C}$ , $I_F = 10\text{ mA}$ , $V_O < 1.0\text{ V}$ , $V_{CM} = 1.5\text{ kV}$ , $R_L = 20\text{ k}\Omega$ , $C_L = 100\text{ pF}$	15			kV/ $\mu\text{s}$

\*1 Typical values at  $T_A = 25^\circ\text{C}$ .

\*2 Test circuit for propagation delay time



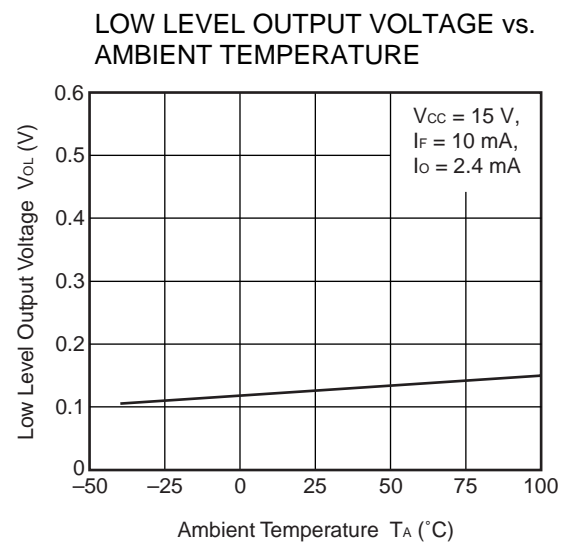
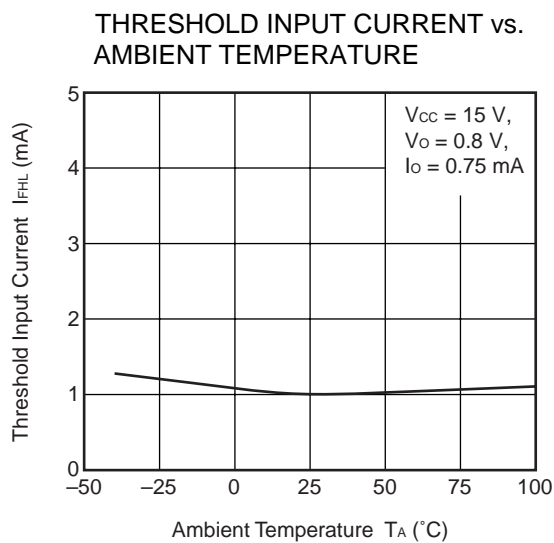
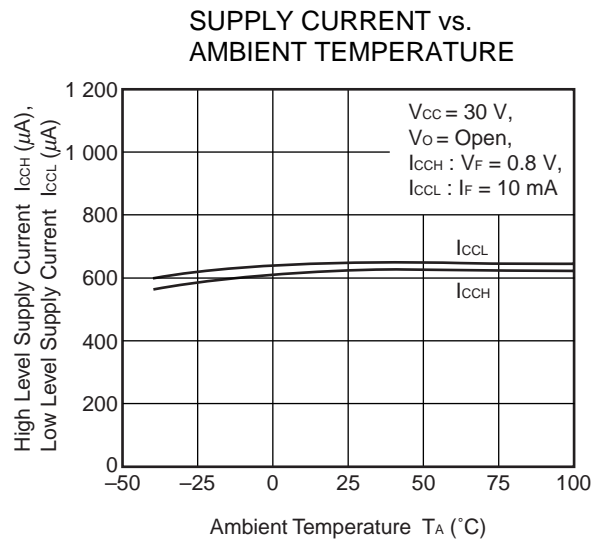
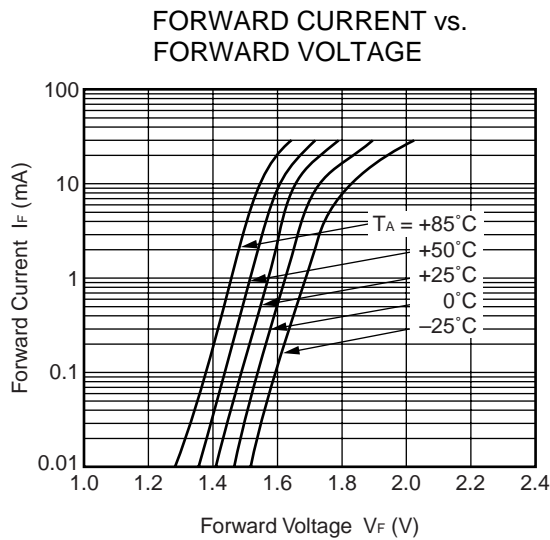
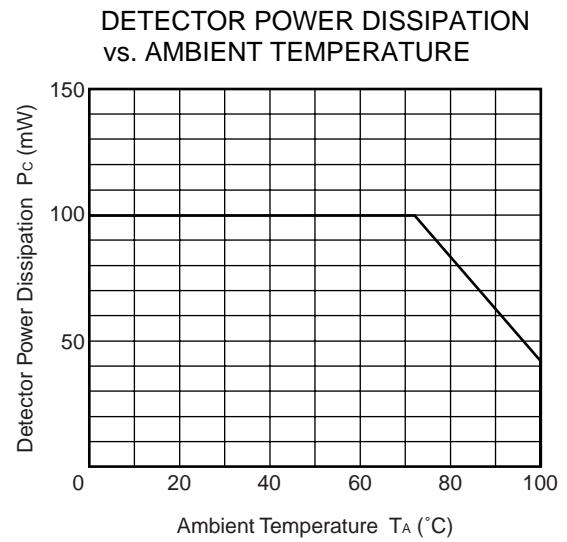
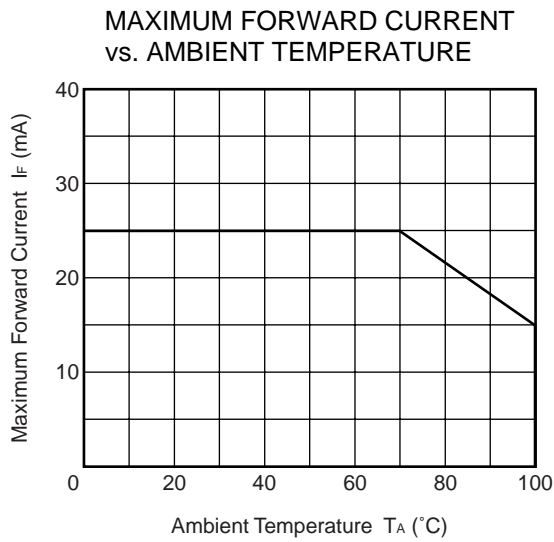
★ \*3 Test circuit for common mode transient immunity



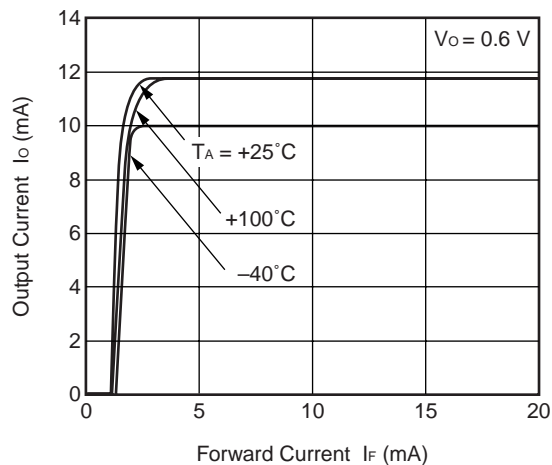
## USAGE CAUTIONS

- ★ 1. This product is weak for static electricity by designed with high-speed integrated circuit so protect against static electricity when handling.
- 2. By-pass capacitor of more than  $0.1\text{ }\mu\text{F}$  is used between  $V_{CC}$  and GND near device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than  $10\text{ mm}$ .

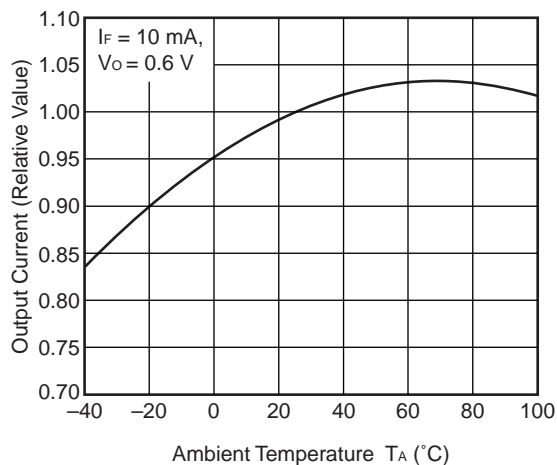
**TYPICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ , unless otherwise specified)**



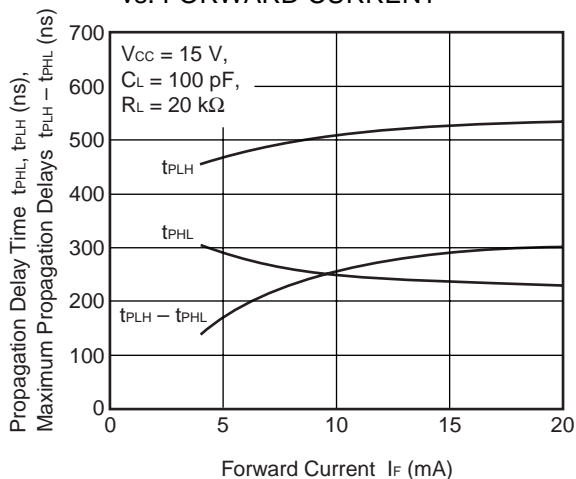
OUTPUT CURRENT vs. FORWARD CURRENT



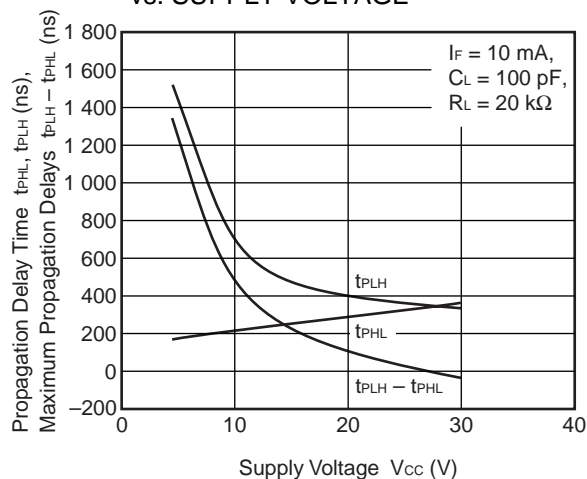
OUTPUT CURRENT vs. AMBIENT TEMPERATURE



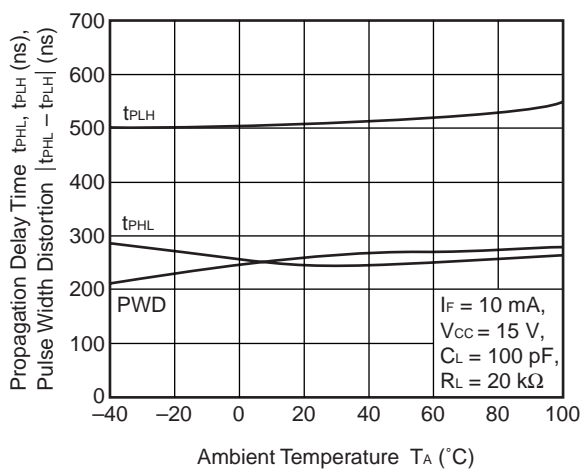
PROPAGATION DELAY TIME, MAXIMUM PROPAGATION DELAYS vs. FORWARD CURRENT



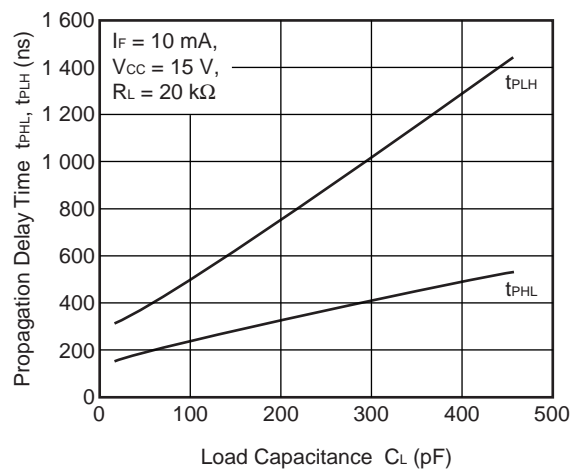
PROPAGATION DELAY TIME, MAXIMUM PROPAGATION DELAYS vs. SUPPLY VOLTAGE



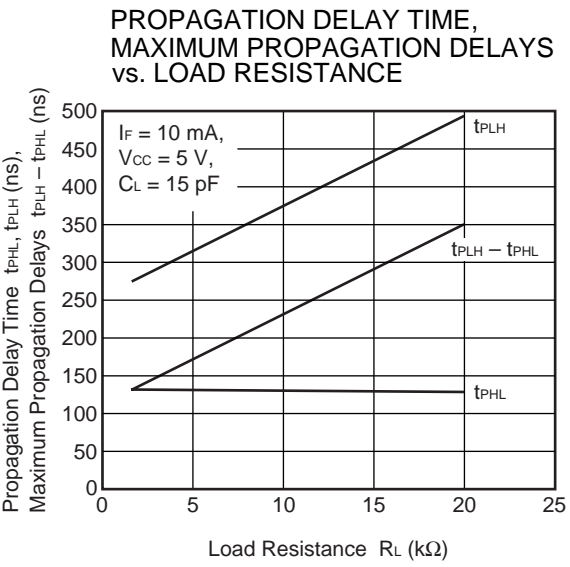
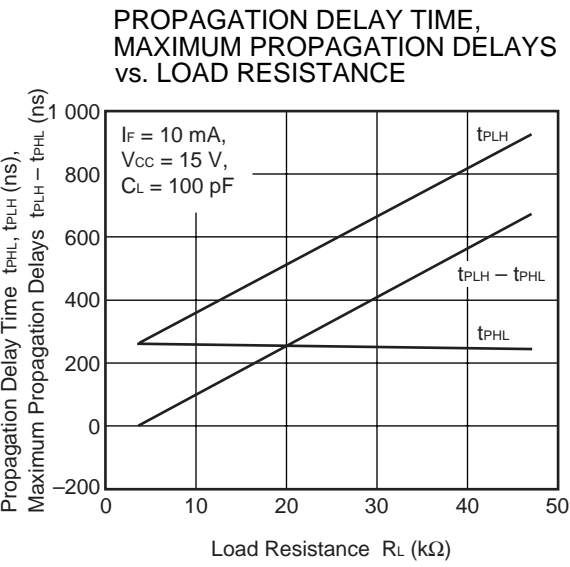
PROPAGATION DELAY TIME, PULSE WIDTH DISTORTION vs. AMBIENT TEMPERATURE



PROPAGATION DELAY TIME vs. LOAD CAPACITANCE



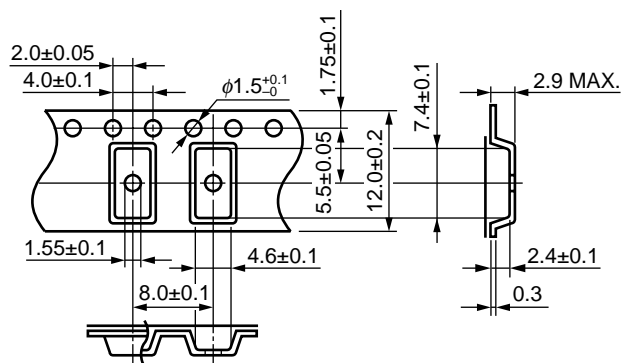




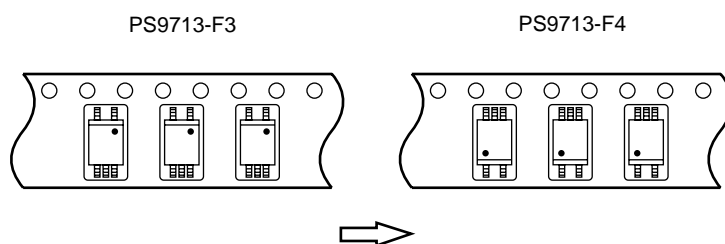
**Remark** The graphs indicate nominal characteristics.

★ TAPING SPECIFICATIONS (UNIT: mm)

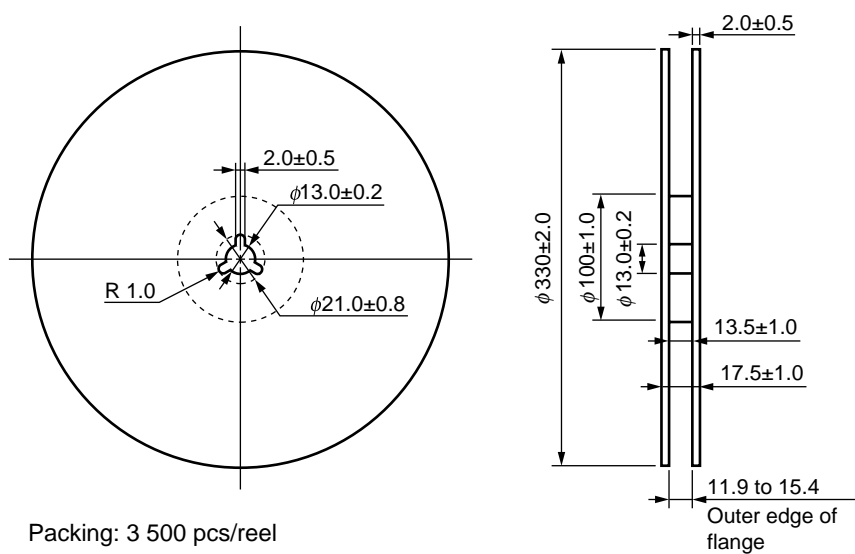
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)

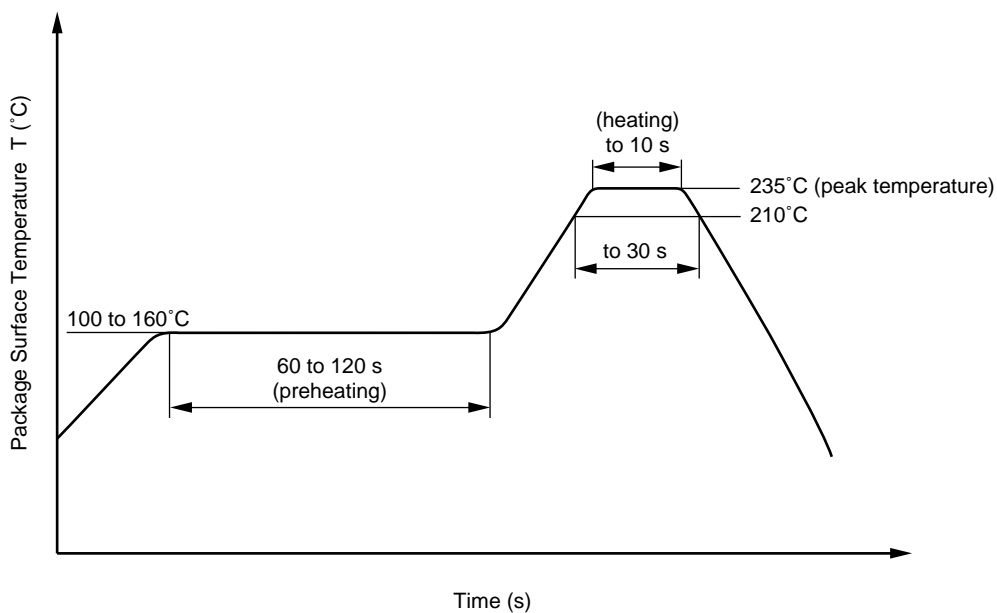


## ★ RECOMMENDED SOLDERING CONDITIONS

### (1) Infrared reflow soldering

- Peak reflow temperature 235°C or below (package surface temperature)
- Time of temperature higher than 210°C 30 seconds or less
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



### (2) Cautions

- Fluxes  
Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

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M8E 00.4-0110

**SAFETY INFORMATION ON THIS PRODUCT**

<b>Caution</b>	GaAs Products	<p>The product contains gallium arsenide, GaAs. GaAs vapor and powder are hazardous to human health if inhaled or ingested.</p> <ul style="list-style-type: none"> <li>• Do not destroy or burn the product.</li> <li>• Do not cut or cleave off any part of the product.</li> <li>• Do not crush or chemically dissolve the product.</li> <li>• Do not put the product in the mouth.</li> </ul> <p>Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.</p>
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► **Business issue**

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► **Technical issue**

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